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(71) Applicant: **DENSO CORP**

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(72) Inventor: **GOTO TSUTOMU**
HARADA YOSHIHARU

**(54) BALL GRID ARRAY SEMICONDUCTOR DEVICE
AND ITS MOUNTING METHOD.**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a mounting method for a BGA semiconductor device, which reforms the warp occurring in the ball grid array(BGA) semiconductor device and attains favorable electric connection.

SOLUTION: In the case of mounting a BGA semiconductor device 1 on a mounting board 2 by this method, adhesives 11, a little higher than the level of a solder bump 10, to join the four corners, at least, of the BGA semiconductor device with the mounting board 2 are made. Then, after hardening of this adhesive 11, heat-treatment is applied to it, with this a supporting pole, and the solder bump 10 is reflowed. At this time, the warp going to occur by heat-treatment is reformed by the adhesive 11, so the mounting without influence of a warp can be performed.

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